Special Issue

Electronic and Photonic Device Integration and Packaging

Message from the Guest Editors

The rapid advancement of electronic and photonic technologies has enabled transformative progress in areas such as high-performance computing, artificial intelligence, optical communication, sensing and advanced manufacturing. Recent developments in heterogeneous integration, chiplet architectures, silicon photonics and advanced packaging techniques, including 2.5D/3D integration, through silicon vias, wafer-level packaging and photonic-electronic co-integration, are opening new possibilities for compact, high-performance and energy-efficient devices. Emerging solutions such as advanced interconnect architectures, novel materials, integrated photonic platforms and in situ monitoring and metrology are playing increasingly important roles in enabling reliable and scalable device integration. To highlight the latest progress in this rapidly evolving field, we are pleased to announce the Special Issue entitled "Electronic and Photonic Device Integration and Packaging." This Special Issue aims to bring together recent advances and emerging research directions in the integration, packaging and reliability of electronic and photonic devices.

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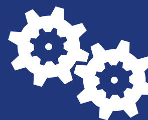
Deadline for manuscript submissions

25 December 2026



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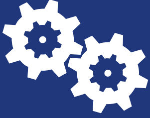

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